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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10050300	FILING DATE 01/15/2002	CLASS 257	SUBCLASS 4501	GAU 2811	EXAMINER J. P. J.
**APPLICANTS: Chen Yen-Ming; Lin Chia-Fu; Fan Yang-Tung; Huang Hong-Wen; Chu Cheng-Yu;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 67,200-571	
Verified and Acknowledged Examiners's initials					
TITLE : Microelectronic fabrication with corrosion inhibited bond pad					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
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